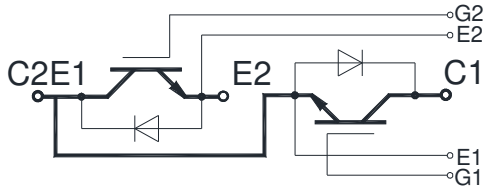




## MRI 600.17-E

### 2 in 1 IGBT Modules



#### Features:

- Low  $V_{CE(sat)}$  Trench IGBT technology
- $V_{CE(sat)}$  with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

#### Typical Applications:

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
$V_{CES}$	Collector-Emitter voltage	$T_j=25^\circ\text{C}$			1700	V
$V_{GES}$	Gate-Emitter voltage	$T_j=25^\circ\text{C}$			$\pm 20$	V
$I_C$	Collector current	Continuous@ $T_C=100^\circ\text{C}$			600	A
$I_{CM}$		$T_P=1\text{ms}$			1200	A
$P_D$	Collector power dissipation	$T_j=175^\circ\text{C}$ , 1 device			4166	W
$T_j$	Junction temperature	/			175	$^\circ\text{C}$
$T_{stg}$	Storage temperature	/	-40		125	$^\circ\text{C}$
$V_{iso}$	Isolation between terminal and copper base	$T_j=25^\circ\text{C}$ , AC: 1minute	4000			V
$I_{CES}$	Zero gate voltage collector current	$T_j=25^\circ\text{C}$ , $V_{CE}=1700\text{V}$ , $V_{GE}=0\text{V}$			5.0	mA
$I_{GES}$	Gate-Emitter leakage current	$T_j=25^\circ\text{C}$ , $V_{CE}=0\text{V}$ , $V_{GE}=\pm 20\text{V}$			400	nA
$V_{GE(th)}$	Gate-Emitter threshold voltage	$T_j=25^\circ\text{C}$ , $V_{CE}=20\text{V}$ , $I_C=12\text{mA}$	5.6	6.2	6.8	V
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j=25^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_C=600\text{A}$		1.85	2.20	V
		$T_j=125^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_C=600\text{A}$		2.25		V
		$T_j=150^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_C=600\text{A}$		2.35		V
$Q_G$	Gate charge	$V_{GE}=\pm 15\text{V}$		4.50		$\mu\text{C}$
$R_{Gint}$	Internal Gate Resistance			1.3		$\Omega$
$C_{ies}$	Input capacitance	$T_j=25^\circ\text{C}$ , $V_{CE}=10\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$		45.9		nF
$C_{res}$	Reverse transfer capacitance			1.4		nF
$t_{on}$	Turn-on Delay time		$T_j=150^\circ\text{C}$ , $V_{CC}=900\text{V}$ , $I_C=600\text{A}$ , $V_{GE}=\pm 15\text{V}$ , $R_G=1.0\Omega$		192	
$t_r$	Rise Time			80		ns
$t_{off}$	Turn-off Delay time			640		ns
$t_f$	Fall Time			216		ns
$E_{on}$	Turn-on Switching Loss			259		mJ
$E_{off}$	Turn-off Switching Loss			215		mJ
$I_{sc}$	SC Date	$T_P \leq 10\mu\text{s}$ , $V_{GE}=15\text{V}$ , $T_j=150^\circ\text{C}$ , $V_{CC}=1000\text{V}$ , $V_{CEM} \leq 1700\text{V}$		2300		A
$t_{sc}$	Short circuit withstand time	$T_j=150^\circ\text{C}$ , $V_{CC}=720\text{V}$ , $V_{GE}=\pm 15\text{V}$ , $R_g=7.5\Omega$	10			$\mu\text{s}$

V <sub>F</sub>	Forward on voltage	T <sub>j</sub> =25°C , I <sub>F</sub> =600A, V <sub>GE</sub> =0V		1.80	2.25	V
		T <sub>j</sub> =125°C , I <sub>F</sub> =600A, V <sub>GE</sub> =0V		1.95		V
		T <sub>j</sub> =150°C , I <sub>F</sub> =600A, V <sub>GE</sub> =0V		1.90		V
I <sub>RM</sub>	Peak Reverse Recovery Current	V <sub>R</sub> =900V, I <sub>F</sub> =600A, -di/dt=7475A/μs, V <sub>GE</sub> =-15V, T <sub>j</sub> =150°C		670		A
Q <sub>r</sub>	Recovered Charge			314		μC
E <sub>rec</sub>	Reverse Recovery Energy			198		mJ
t <sub>rr</sub>	Reverse recovery time	T <sub>j</sub> =150°C , I <sub>F</sub> =600A		1160		ns
R <sub>th(j-c)</sub>	Thermal resistance	per IGBT			0.036	°C/W
		per Diode			0.128	°C/W
R <sub>th(c-f)</sub>	Contact thermal resistance (per module)	With thermal compound		0.009		°C/W
R <sub>25</sub>	Rated Resistance	T <sub>j</sub> =25°C		5.0		kΩ
ΔR/R	Deviation of R <sub>100</sub>	T <sub>C</sub> =100°C, R <sub>100</sub> =493.3Ω	-5		5	%
P <sub>25</sub>	Power Dissipation	Continuous@ T <sub>C</sub> =100°C			20.0	mW
B <sub>25/50</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/50</sub> (1/T <sub>2</sub> -1/(298.15K))]		3375		K
B <sub>25/80</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/80</sub> (1/T <sub>2</sub> -1/(298.15K))]		3411		K
B <sub>25/100</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/100</sub> (1/T <sub>2</sub> -1/(298.15K))]		3433		K
Screw torque	Mounting(M6)	/	3		6.0	N·m
	Terminals(M5)	/	3		6.0	N·m
W <sub>t</sub>	Weight				350	g
Outline	465H3P					

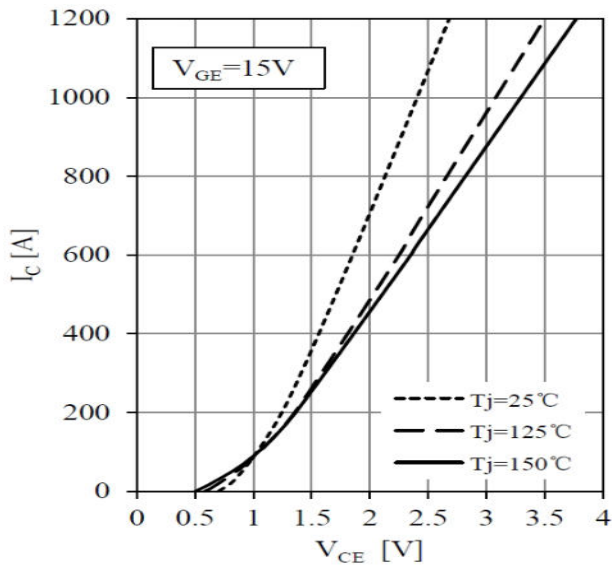


Fig 1. IGBT Output Characteristics

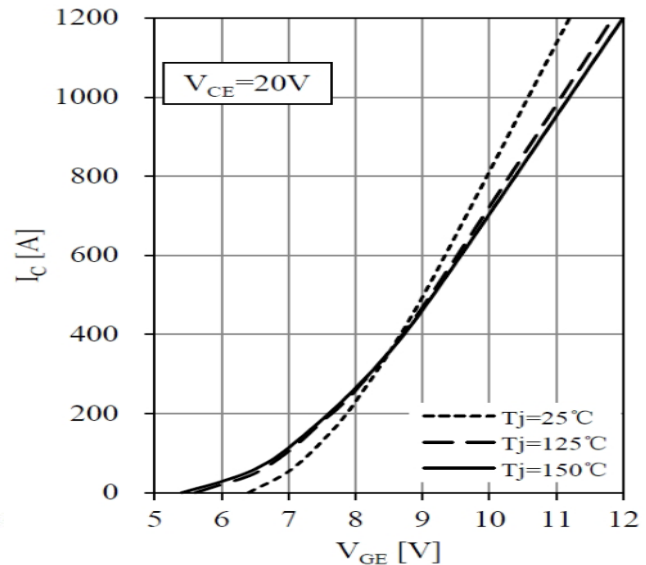


Fig 2. IGBT Transfer Characteristics

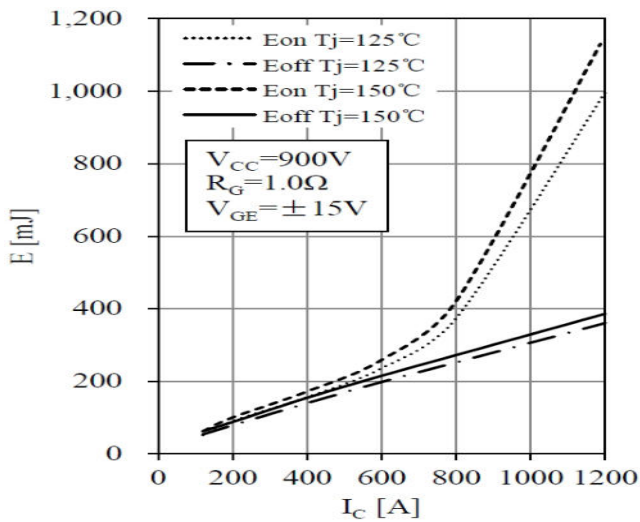


Fig 3. IGBT Switching Loss vs. Ic

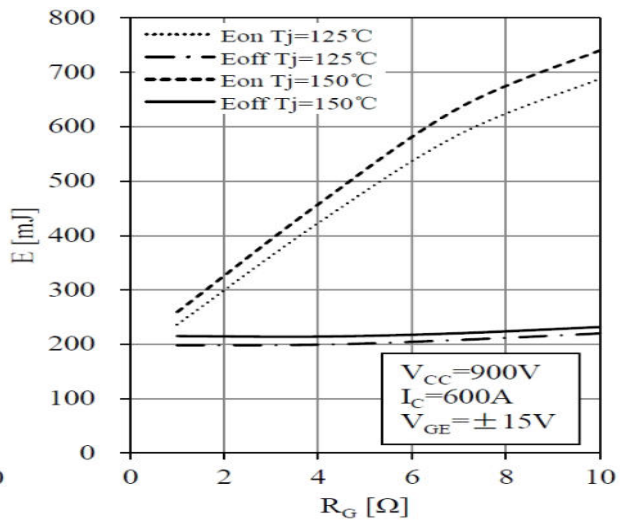


Fig 4. IGBT Switching Loss vs. Rg

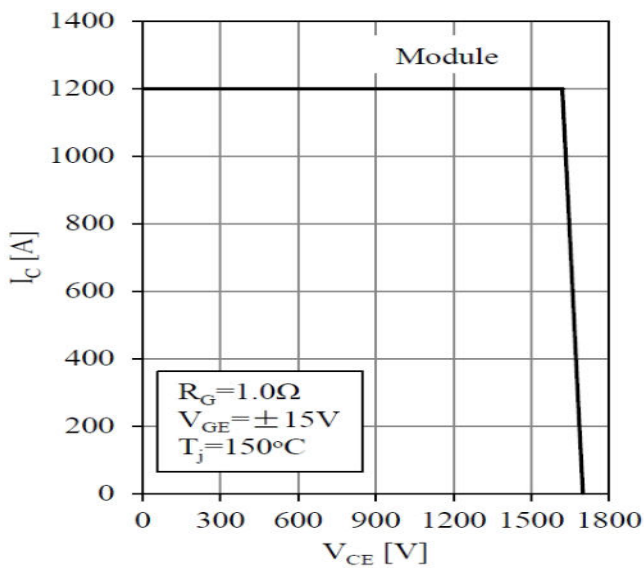


Fig 5. RBSOA

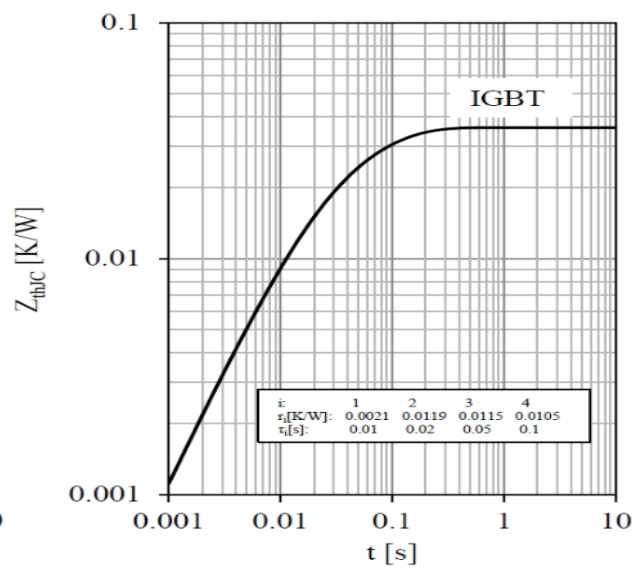


Fig 6. IGBT Transient Thermal Impedance

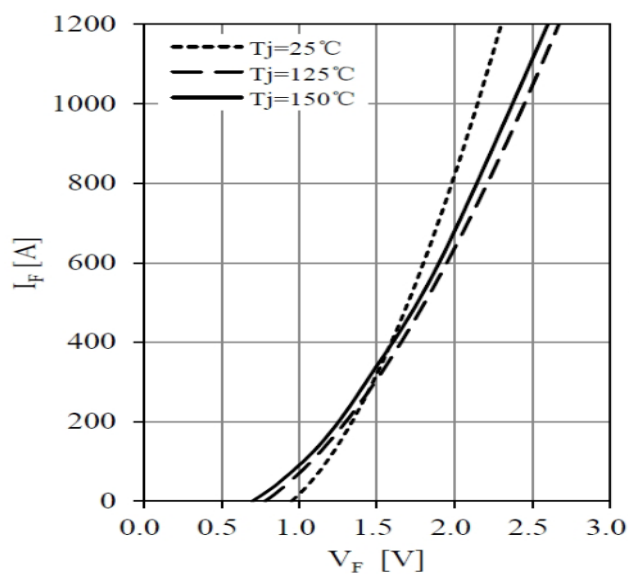


Fig 7. Diode Forward Characteristics

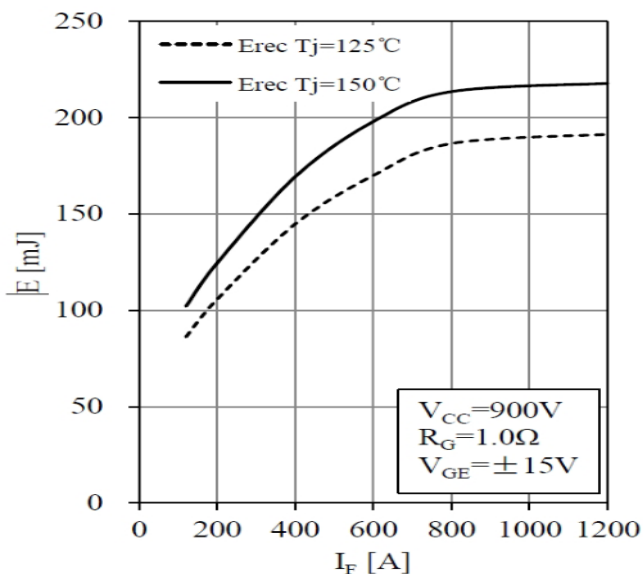


Fig 8. Diode Switching Loss vs. If

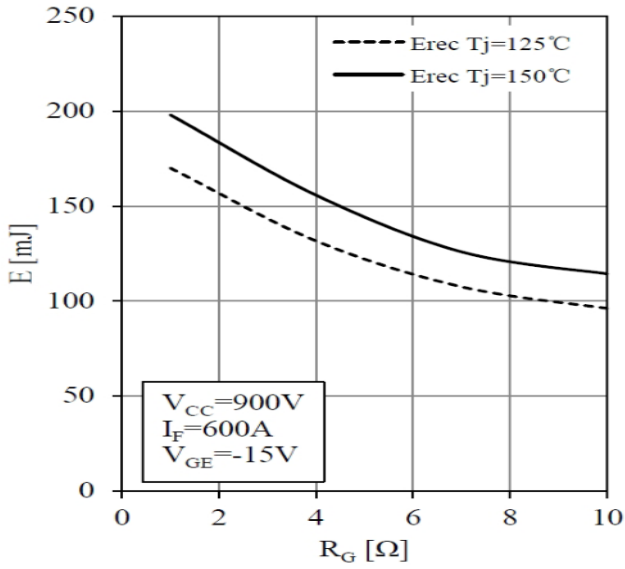


Fig 9. Diode Switching Loss vs.  $R_G$

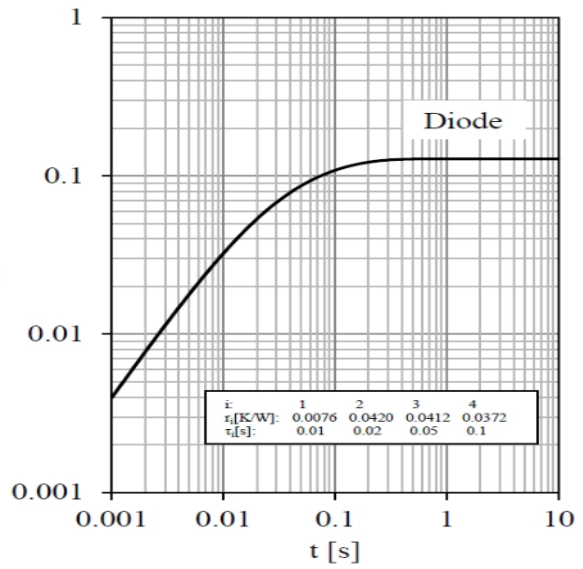


Fig 10. Diode Transient Thermal Impedance

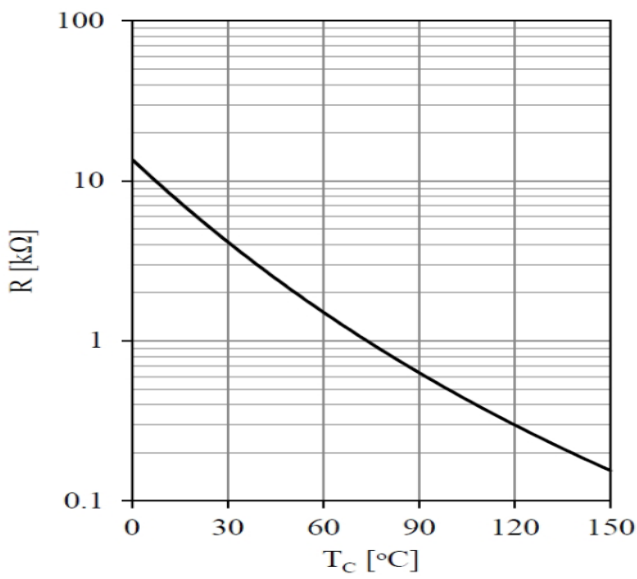


Fig 11. NTC Temperature Characteristic

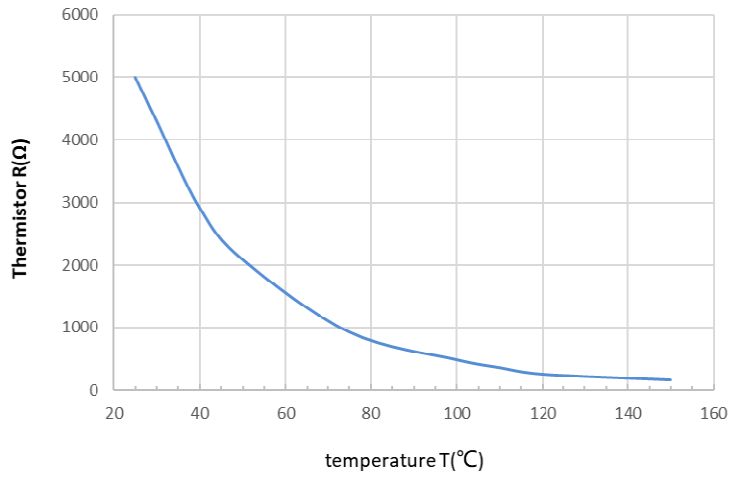
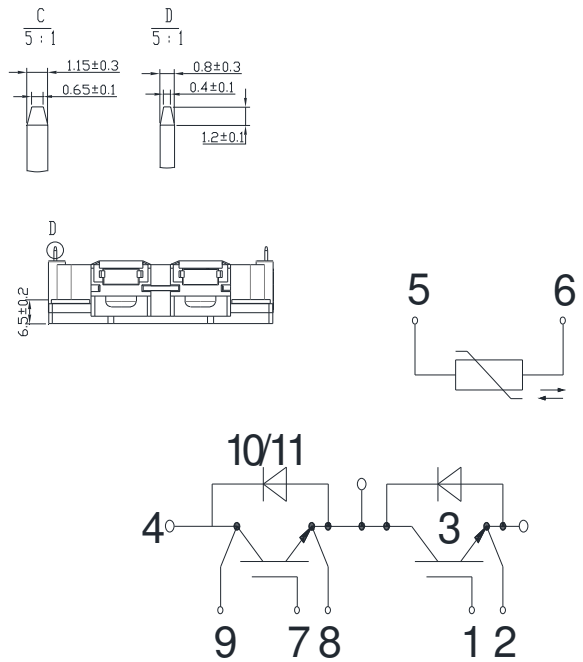
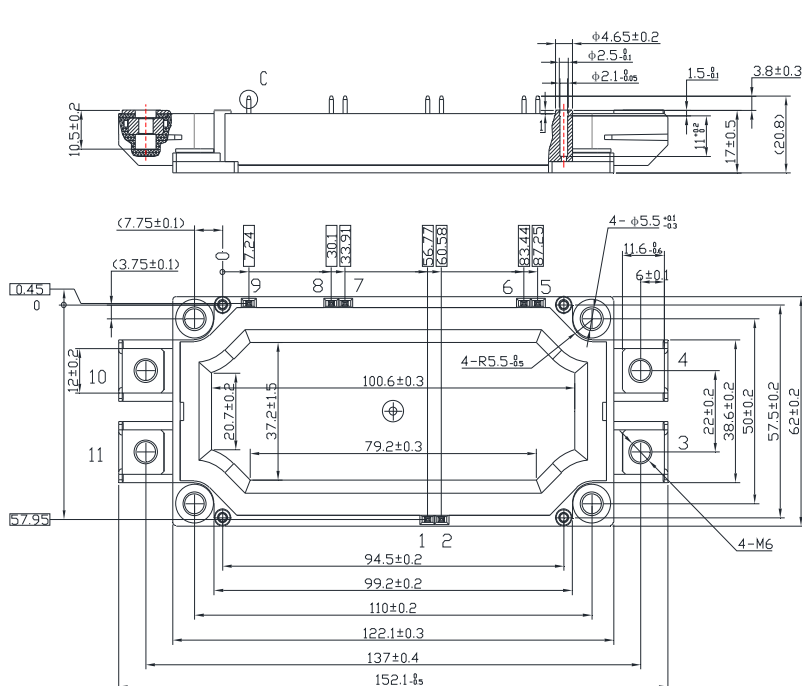


Fig 12. Thermistor Vs. temperature



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